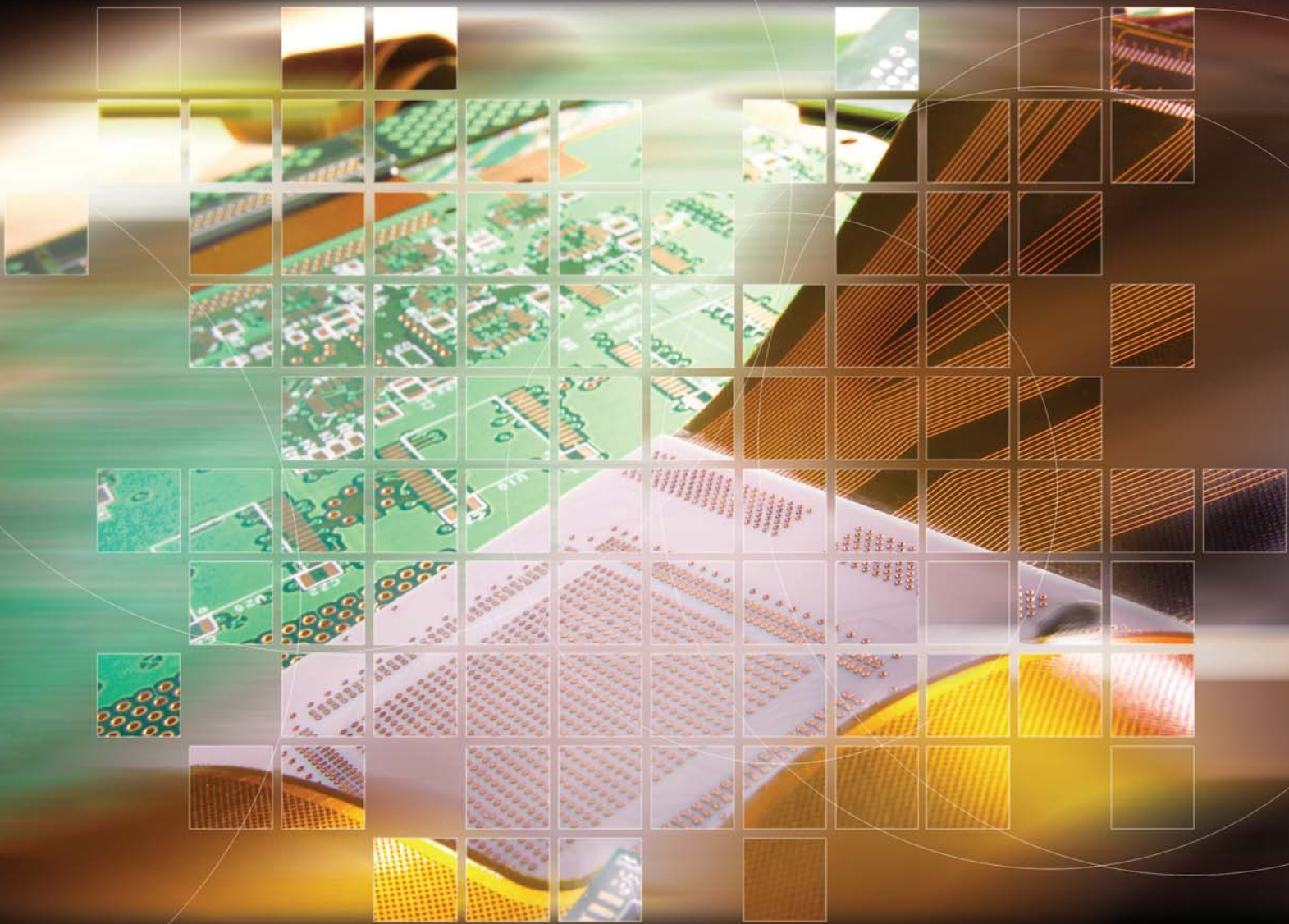


# RIGID FLEX

HIGH LAYER COUNT • HIGH SPEED • HDI



*More than a decade's experience in the design and manufacture of the highest quality rigid flex boards.*

**compunetics**  
excellence, measured in microns.

## RIGID FLEX

# Compunetics provides engineered solutions for the most complex rigid flex needs.

With design and manufacturing all under one roof, the Compunetics team is able to produce rigid flex boards of unparalleled quality and complexity. Compunetics' track record of innovation and strict attention to detail has made us the preferred choice of the most demanding clients.

Features include:

- Embedded resistor tolerance to  $\pm 10\%$
- Thickness up to 20 layers
- Controlled impedance
- All-polyimide bond ply

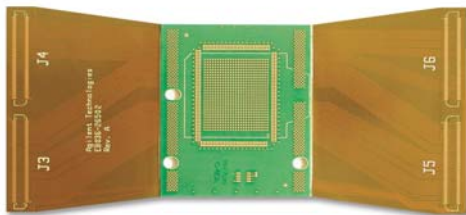
Applications include:

- Military
- Semiconductors
- Microprocessor testing
- Next generation silicon testing
- Supercomputing
- Aerospace
- Miniaturization
- Reliability enhancement

### COMMERCIAL

#### Silicon Testing

Layers: 14 rigid; 3 flex  
Material: High Speed FR4 (Isola 408)  
Dupont AP Flex material  
Trace Width: 0.002 +/- 0.0003"  
Controlled Impedance (64 ohms +/- 10%)  
Buried resistors (400 each of Ohmega  
60 ohm +/- 10%)  
Buried capacitors (900 each)  
Surface Finish: Entec 106



#### Avionics

Layers: 8 'Looseleaf' Design  
Finish: 3 Double-Sided Flex Cores with Coverlay  
2-Ounce Copper on Flex  
Military Specification



### MILITARY

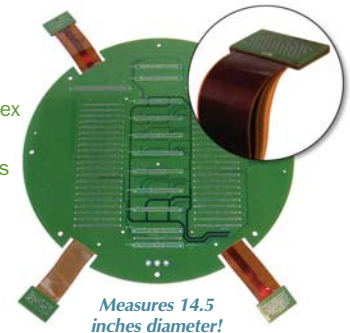
#### Ordinates Control

Layers: 10  
Finish: 2-Ounce Copper  
Military Specification



#### Military

Layers: 22 'Looseleaf' Design  
Material: Polyimide Rigid  
DuPont AP Flex  
Certifications: Meets 50884  
Specifications  
Surface Finish: HAL



Measures 14.5 inches diameter!

#### Satellite Systems

Layers: 12  
Trace/Space: 6/6 (150/150  $\mu\text{m}$ )  
Finish: Immersion Gold  
Material: Polyimide Rigid  
DuPont AP Flex



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